

# IXTQ42N25P-VB Datasheet

## N-Channel 200-V (D-S) MOSFET

### PRODUCT SUMMARY

$V_{(BR)DSS}$ (V)	$R_{DS(on)}$ ( $\Omega$ )	$I_D$ (A)	$Q_g$ (Typ.)
200	0.048 at $V_{GS} = 15$ V	60	57
	0.046 at $V_{GS} = 10$ V	55	

### FEATURES

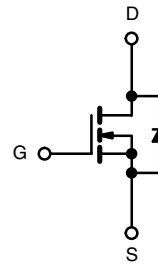
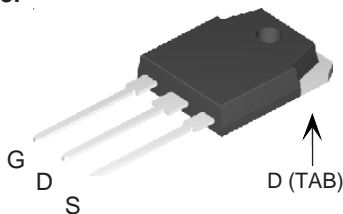
- Trench Power MOSFETS
- 175 °C Junction Temperature
- 100 %  $R_g$  and UIS Tested


**RoHS**  
 COMPLIANT

### APPLICATIONS

- Power Supply
- Lighting Systems

TO-3P



N-Channel MOSFET

### ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	200	V
Gate-Source Voltage	$V_{GS}$	$\pm 25$	
Continuous Drain Current ( $T_J = 175$ °C)	$I_D$	60	A
		40	
Pulsed Drain Current	$I_{DM}$	180	
Single Pulse Avalanche Current	$I_{AS}$	20	
Single Pulse Avalanche Energy <sup>a</sup>	$E_{AS}$	20	mJ
Maximum Power Dissipation <sup>a</sup>	$P_D$	166 <sup>b</sup>	W
		3.12	
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	- 55 to 175	°C

### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Limit	Unit
Junction-to-Ambient (PCB Mount) <sup>c</sup>	$R_{thJA}$	40	°C/W
Junction-to-Case (Drain)	$R_{thJC}$	0.75	

Notes:

a. Duty cycle  $\leq 1$  %.

b. See SOA curve for voltage derating.

c. When Mounted on 1" square PCB (FR-4 material).

**SPECIFICATIONS**  $T_J = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	200			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2.5		4.5		
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 20 V			± 100	nA	
		V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 25 V			± 300		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V			1	μA	
		V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 100 °C			25		
		V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C			250		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> ≥ 10 V, V <sub>GS</sub> = 10 V	40			A	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.048		Ω	
		V <sub>GS</sub> = 15 V, I <sub>D</sub> = 20 A		0.046			
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 100 °C		0.088			
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 150 °C		0.120			
Forward Transconductance <sup>a</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A	25			S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz		3100		pF	
Output Capacitance	C <sub>oss</sub>			300			
Reverse Transfer Capacitance	C <sub>rss</sub>			135			
Total Gate Charge <sup>c</sup>	Q <sub>g</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 15 V, I <sub>D</sub> = 50 A		85	127	nC	
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 50 A		57	85		
	Gate-Source Charge <sup>c</sup>		Q <sub>gs</sub>		14		
	Gate-Drain Charge <sup>c</sup>		Q <sub>gd</sub>		20		
Gate Resistance	R <sub>g</sub>	f = 1 MHz		1.2	1.8	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>	V <sub>DD</sub> = 100 V, R <sub>L</sub> = 2 Ω I <sub>D</sub> ≅ 50 A, V <sub>GEN</sub> = 10 V, R <sub>g</sub> = 1 Ω		16	25	ns	
Rise Time <sup>c</sup>	t <sub>r</sub>			170	260		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			27	42		
Fall Time <sup>c</sup>	t <sub>f</sub>			9	18		
Source-Drain Diode Ratings and Characteristics <sup>c</sup> T <sub>C</sub> = 25 °C							
Continuous Current	I <sub>S</sub>				36	A	
Pulsed Current	I <sub>SM</sub>				80		
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 20 A, V <sub>GS</sub> = 0 V		0.86	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 40 A, di/dt = 100 A/μs		116	175	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>			9	14	A	
Reverse Recovery Charge	Q <sub>rr</sub>			0.53	0.8	μC	
Reverse Recovery Fall Time	t <sub>a</sub>			84		nS	
Reverse Recovery Rise Time	t <sub>b</sub>			32			

Notes:

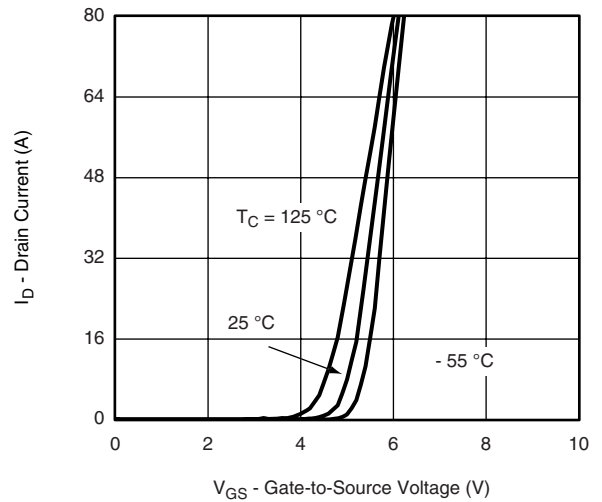
- a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .  
 b. Guaranteed by design, not subject to production testing.  
 c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

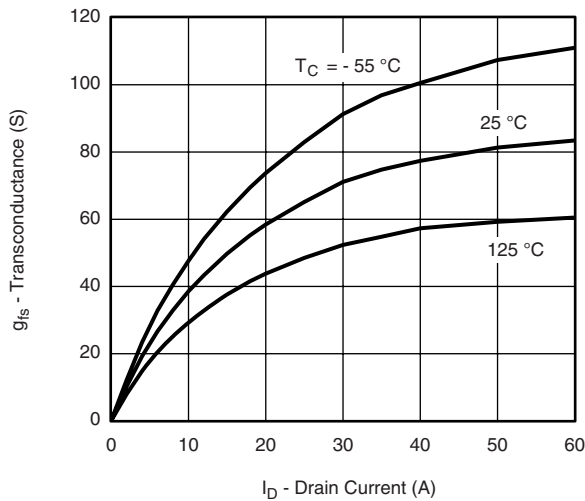
**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted



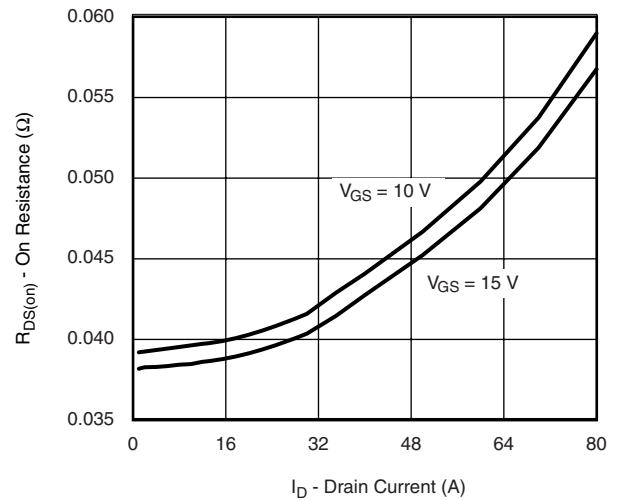
**Output Characteristics**



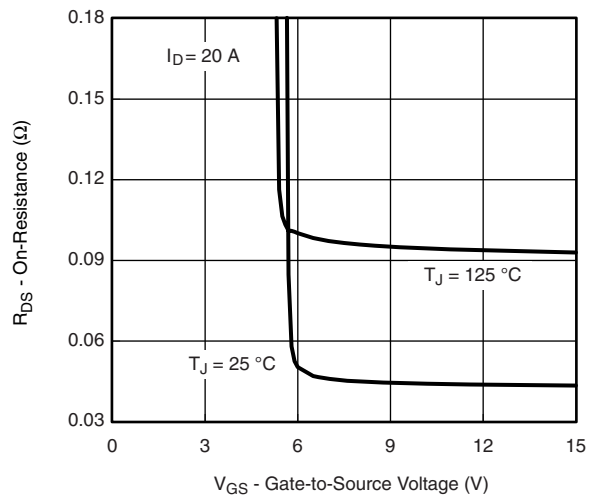
**Transfer Characteristics**



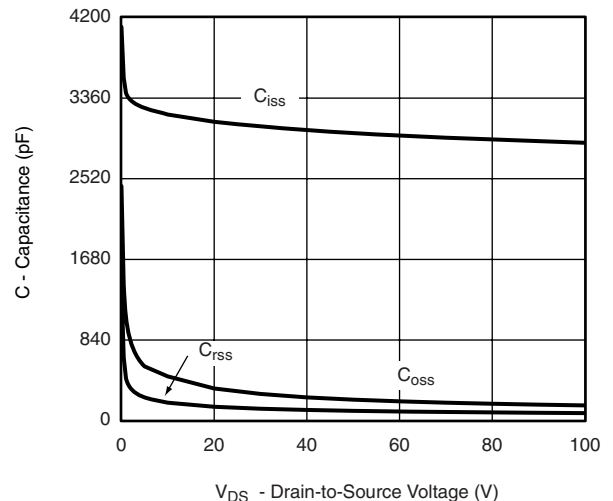
**Transconductance**



**On-Resistance vs. Drain Current**

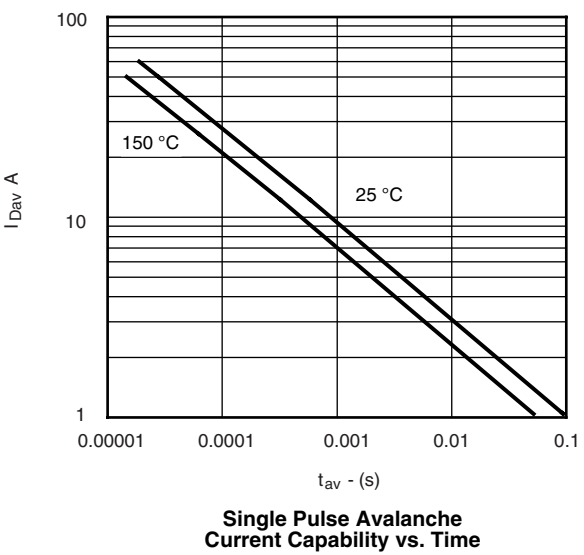
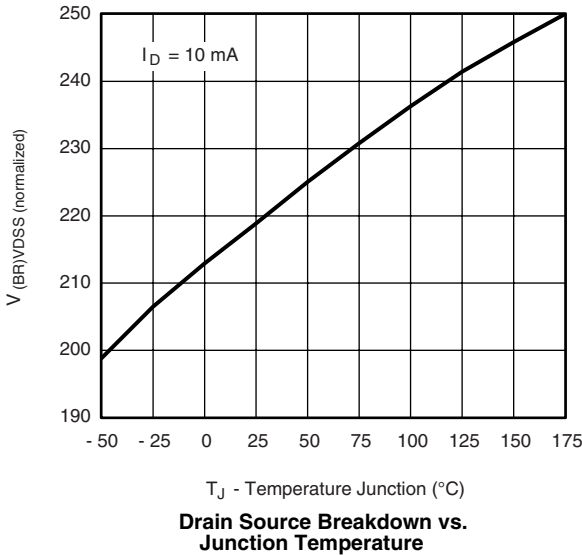
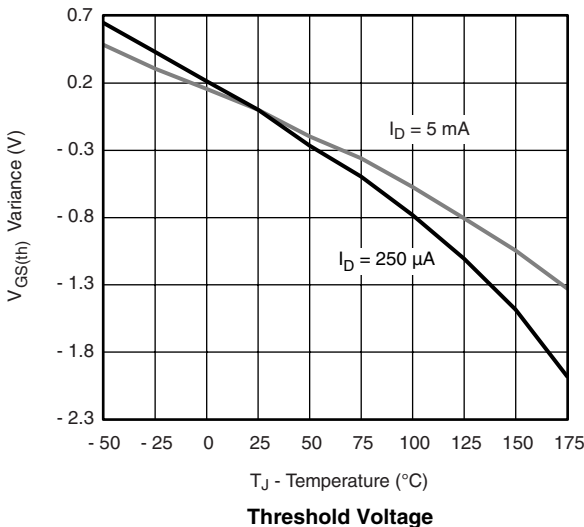
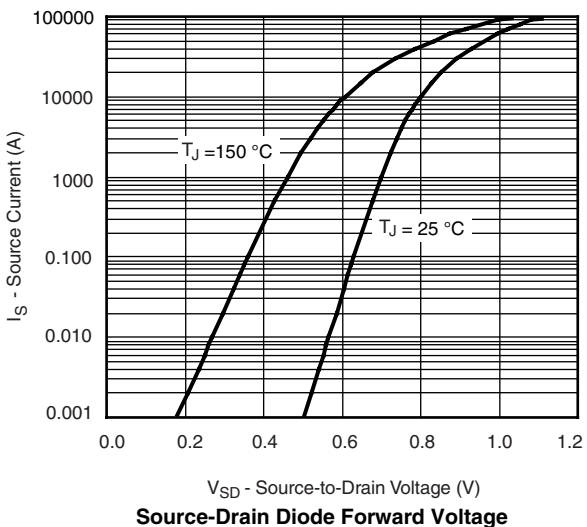
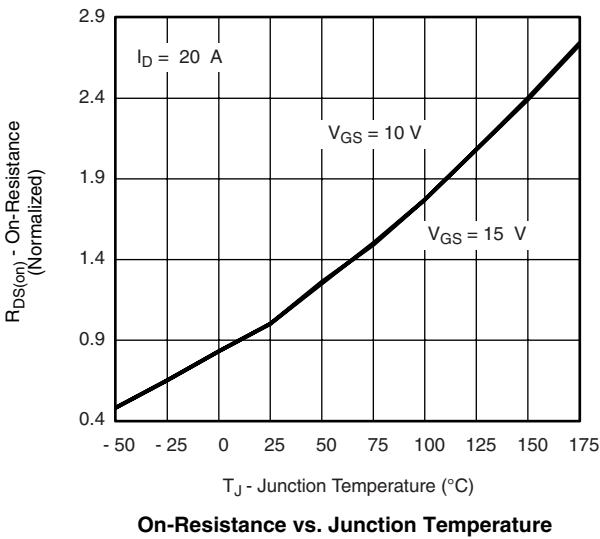
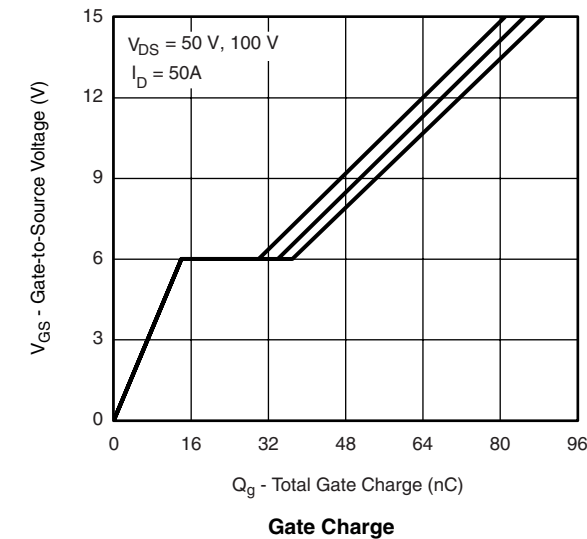


**On-Resistance vs. Gate-to-Source Voltage**

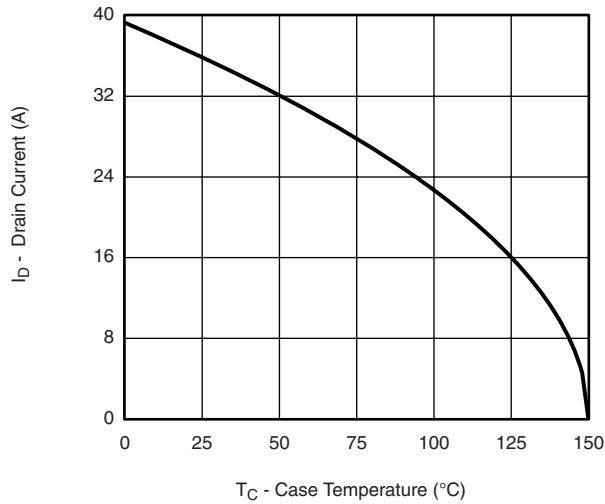


**Capacitance**

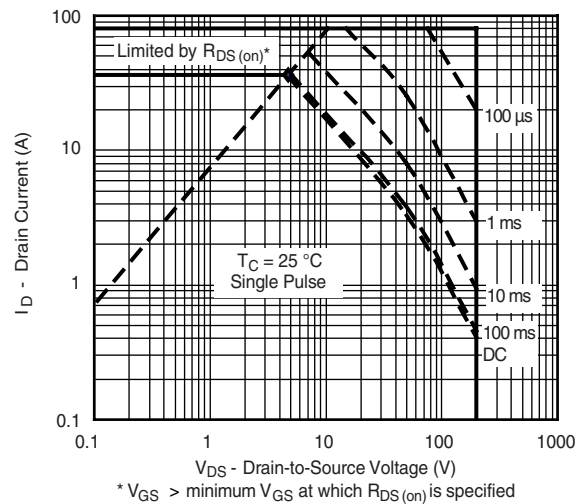
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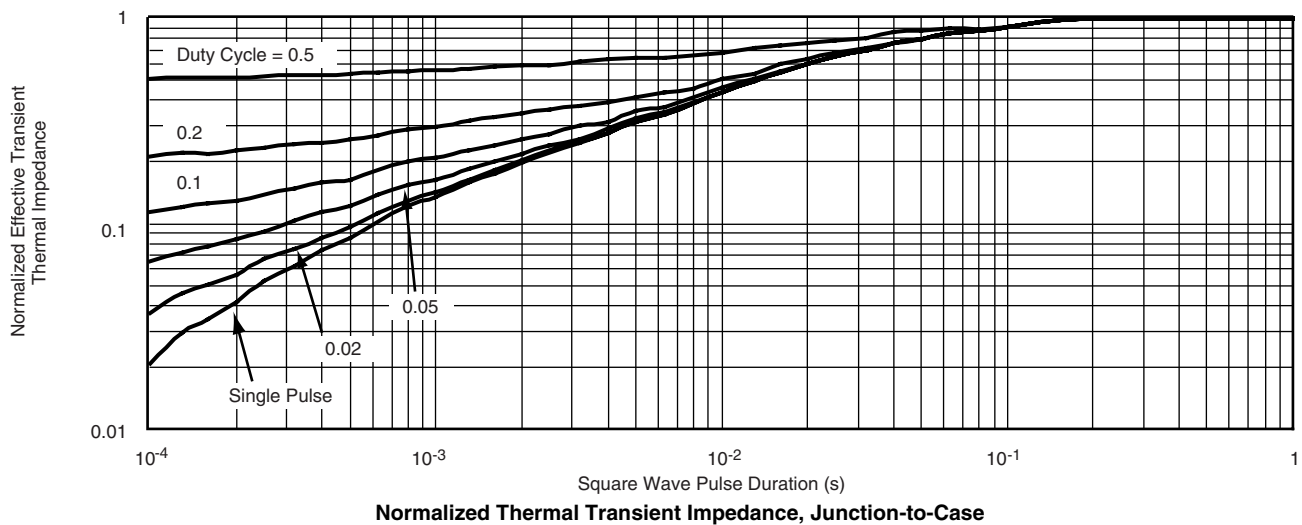
**THERMAL RATINGS**



**Maximum Drain Current vs. Case Temperature**

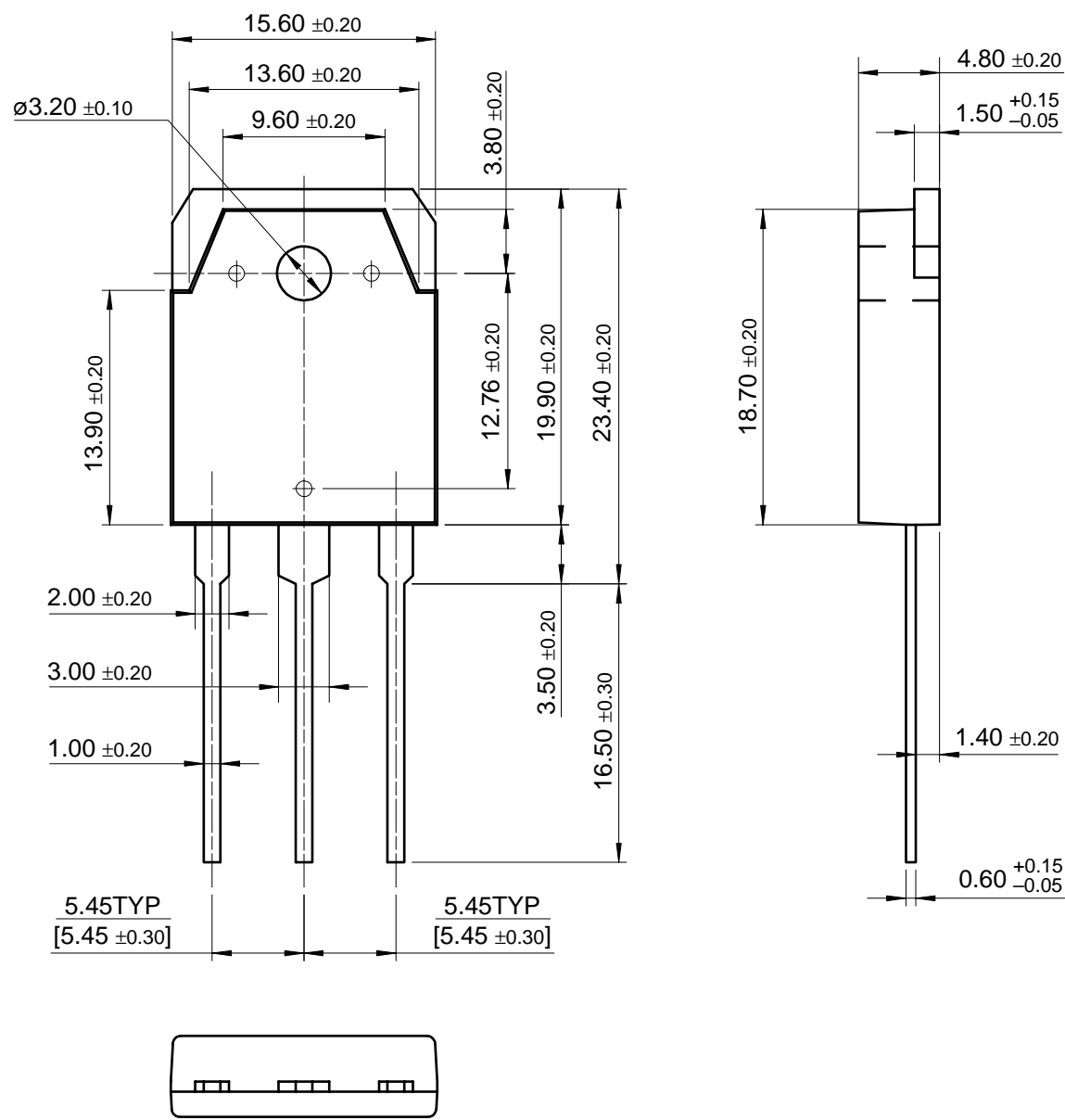


**Safe Operating Area**



**Normalized Thermal Transient Impedance, Junction-to-Case**

TO-3P



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